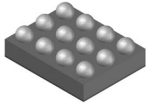
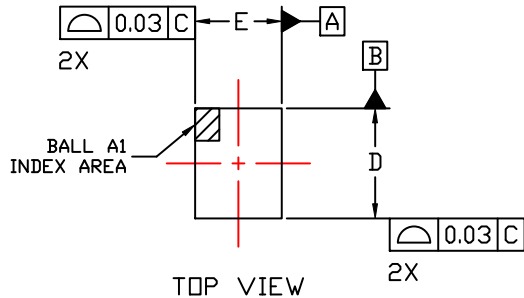


MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS



WLCSP12 1.07x1.36x0.432, 0.35P
CASE 567GK
ISSUE O

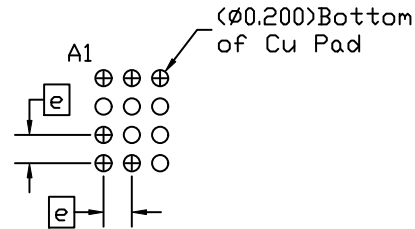
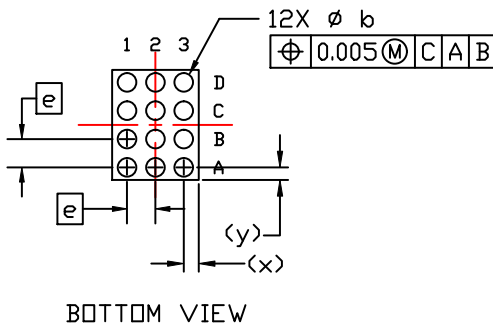
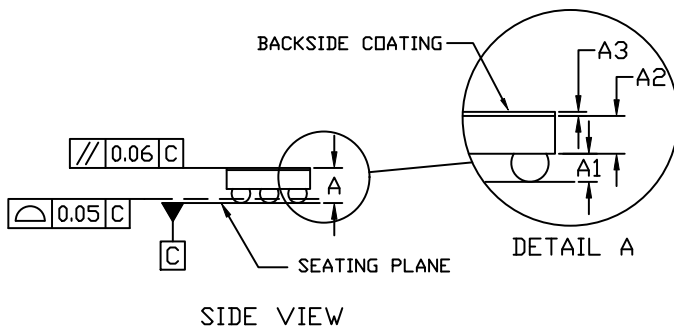
DATE 09 NOV 2021



NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2009
2. CONTROLLING DIMENSION: MILLIMETERS
3. DATUM C IS DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.

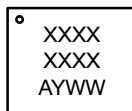
DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	0.391	0.432	0.473
A1	0.154	0.174	0.194
A2	0.215	0.233	0.251
A3	0.022	0.025	0.028
b	0.211	0.231	0.251
D	1.330	1.360	1.390
E	1.040	1.070	1.100
e	0.35 BSC		
x	0.170	0.185	0.200
y	0.140	0.155	0.170



**RECOMMENDED MOUNTING FOOTPRINT*
(NSMD PAD TYPE)**

*FOR ADDITIONAL INFORMATION ON OUR Pb-FREE STRATEGY AND SOLDERING DETAILS, PLEASE DOWNLOAD THE ON SEMICONDUCTOR SOLDERING AND MOUNTING TECHNIQUES REFERENCE MANUAL, SOLDERM/D.

GENERIC MARKING DIAGRAM*



XXXX = Specific Device Code
A = Assembly Location
Y = Year
W = Work Week

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

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DESCRIPTION:	WLCSP12 1.07x1.36x0.432, 0.35P	PAGE 1 OF 1

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